

TDS4A212MX, TDS4B212MX

1. Functional Description

- 1-32Gbps 1-Lane Two Differential Channel, 2:1 Mux/1:2 De-Mux

2. General

TDS4A212MX, TDS4B212MX are high-speed differential channel multiplexer(Mux)/demultiplexer(De-Mux) switches. These devices are designed to support up to 32Gbps high-speed differential interfaces such as PCIe® 5.0, CXL 2.0, USB4® Version 2.0, Thunderbolt™ 4, DisplayPort™ 2.0.

TDS4A212MX and TDS4B212MX have different pin assignment. TDS4B212MX has an optimized pin assignment to achieve high frequency performance, while TDS4A212MX's pin assignment is easy to use for board layout.

The A Port (An+, An-) is connected to either the B Port (Bn+, Bn-) or C Port (Cn+, Cn-), which is determined by the combination of both the select (SEL) and output enable (\overline{OE}). When the output enable (\overline{OE}) is held at a high-level, the switches are open (high-impedance state), regardless of the state of the select, thus these devices have lower consumption current.

The devices are designed to operate in temperatures from -40 °C to 105 °C and can be used for application including industrial use cases.

3. Features

- (1) Operating voltage: $V_{CC} = 1.6$ to 3.6 V
- (2) Operating temperature : $T_{opr} = -40$ to 105 °C
- (3) Low current consumption For active mode (Typ.) : $I_{ope} = 60$ μ A,
For standby mode (Max) : $I_{STB} = 10$ μ A
- (4) -3-dB Bandwidth (differential) $BW_{(Diff)}$ (Typ.) : TDS4B212MX = 27.5 GHz
TDS4A212MX = 26.2 GHz
- (5) Differential insertion Loss DDIL (Typ.) : TDS4B212MX = -1.3 dB @ $f = 16$ GHz
TDS4A212MX = -1.4 dB @ $f = 16$ GHz
- (6) Differential return Loss DDRL (Typ.) : TDS4B212MX = -16 dB @ $f = 16$ GHz
TDS4A212MX = -18 dB @ $f = 16$ GHz
- (7) Differential Off Isolation DDOIRR (Typ.) : TDS4B212MX = -14 dB @ $f = 16$ GHz
TDS4A212MX = -11 dB @ $f = 16$ GHz
- (8) Differential Crosstalk DDXT (Typ.) : TDS4B212MX = -36 dB @ $f = 16$ GHz
TDS4A212MX = -30 dB @ $f = 16$ GHz
- (9) Package: XQFN16

4. Interfaces

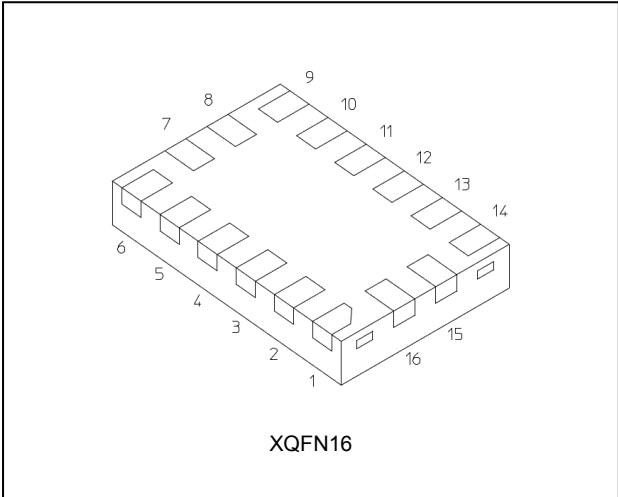
- PCIe 5.0/4.0
- Thunderbolt 4/3
- CXL 2.0/1.0
- DisplayPort 2.0/1.4
- USB4 Version 2.0, Gen3/Gen2
- USB 3.2 Gen 2/Gen 1
- SAS 3.0

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Start of commercial production

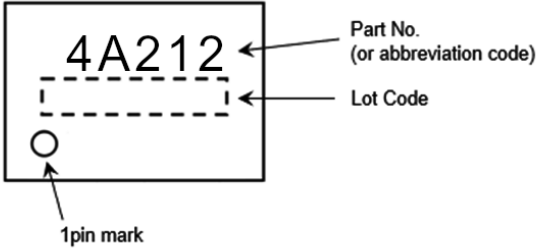
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5. Packaging

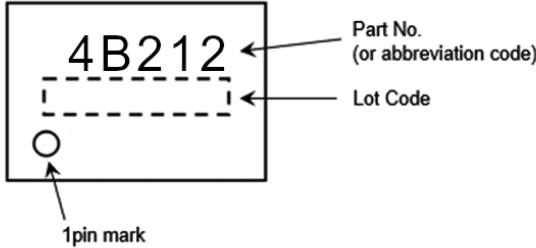


6. Marking

TDS4A212MX

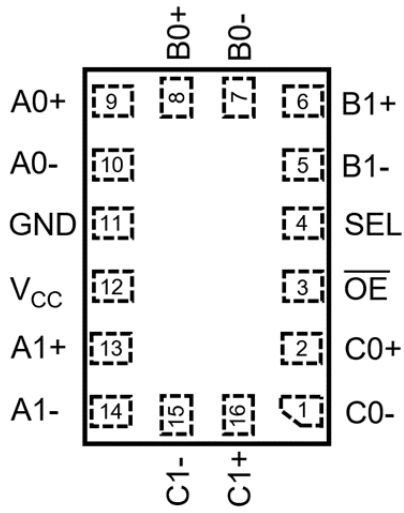


TDS4B212MX



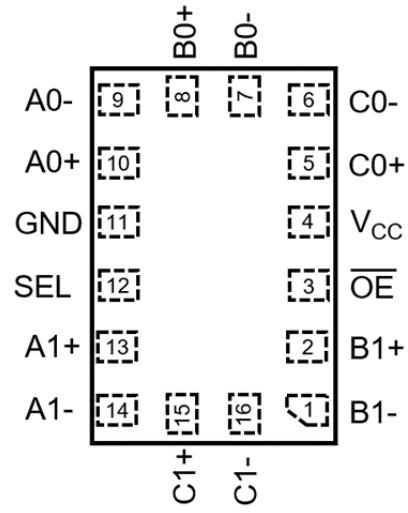
7. Pin Assignment

TDS4A212MX



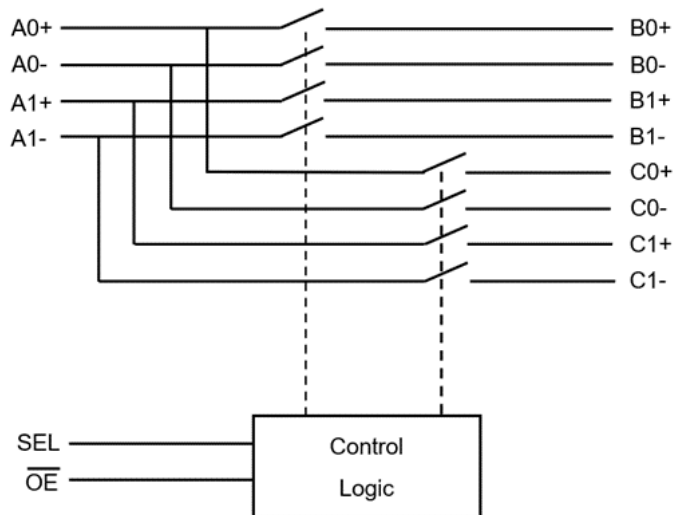
(Top view)

TDS4B212MX



(Top view)

8. Block Diagram



9. Truth Table

Inputs \overline{OE}	Inputs SEL	Function
L	L	An+ port = Bn+ port, An- port = Bn- port (n=0,1)
L	H	An+ port = Cn+ port, An- port = Cn- port (n=0,1)
H	—	An, Bn, Cn port Disconnect (n=0,1)

—: Don't care

10. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	-0.5 to 4.0	V
Input voltage (\overline{OE} , SEL)	V_{IN}	-0.5 to 4.0	V
Switch I/O voltage	V_S	-0.5 to 2.5	V
Switch I/O current	I_S	32	mA
Power dissipation	P_D	180	mW
V_{CC} /ground current	I_{CC}/I_{GND}	± 50	mA
Storage temperature	T_{stg}	-65 to 150	$^{\circ}C$

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

11. Operating Ranges (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	1.6 to 3.6	V
Input voltage (\overline{OE} , SEL)	V_{IN}	0 to 3.6	V
Signal pins differential voltage.	$V_{I/O(Diff)}$	0 to 1.8	V
Signal pins common mode voltage.	$V_{I/O(Com)}$	0 to 2.0	V
Operating temperature	T_{opr}	-40 to 105	$^{\circ}C$
Input rise and fall times	dt/dv	0 to 10	ns/V

Note: The operating ranges must be maintained to ensure the normal operation of the device.

Unused control inputs must be tied to either V_{CC} or GND.

12. Electrical Characteristics

12.1. DC Characteristics

12.1.1. DC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 85 °C)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage (\overline{OE} , SEL)	V_{IH}	—	1.65 to 3.6	$0.65 \times V_{CC}$	—	—	V
Low-level input voltage (\overline{OE} , SEL)	V_{IL}	—	1.65 to 3.6	—	—	$0.35 \times V_{CC}$	V
Input leakage current (\overline{OE} , SEL)	I_{IN}	$V_{IN} = 0$ to 3.6 V	1.65 to 3.6	—	—	± 1	μA
Switch OFF-state leakage current	I_{SZ}	$V_S = 0$ to 2.5 V, $\overline{OE} = V_{CC}$	1.65 to 3.6	—	—	± 3	μA
ON-resistance	R_{ON}	$V_S = 0$ V, $I_S = 8$ mA (TDS4A212)	3.0	—	—	8.4	Ω
		$V_S = 0$ V, $I_S = 8$ mA (TDS4B212)	3.0	—	—	7.9	
		$V_S = 2$ V, $I_S = 8$ mA	3.0	—	—	15	
Standby current	I_{STB}	$\overline{OE} = V_{CC}$, SEL = V_{CC} or GND	3.6	—	—	10	μA
Current consumption	I_{ope}	$\overline{OE} = GND$, SEL = V_{CC} or GND	3.6	—	60	150	μA

Note : All typical values are at $T_a = 25$ °C.

12.1.2. DC Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to 105 °C)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage (\overline{OE} , SEL)	V_{IH}	—	1.65 to 3.6	$0.65 \times V_{CC}$	—	—	V
Low-level input voltage (\overline{OE} , SEL)	V_{IL}	—	1.65 to 3.6	—	—	$0.35 \times V_{CC}$	V
Input leakage current (\overline{OE} , SEL)	I_{IN}	$V_{IN} = 0$ to 3.6 V	1.65 to 3.6	—	—	± 1	μA
Switch OFF-state leakage current	I_{SZ}	$V_S = 0$ to 2.5 V, $\overline{OE} = V_{CC}$	1.65 to 3.6	—	—	± 4	μA
ON-resistance	R_{ON}	$V_S = 0$ V, $I_S = 8$ mA (TDS4A212)	3.0	—	—	8.9	Ω
		$V_S = 0$ V, $I_S = 8$ mA (TDS4B212)	3.0	—	—	8.4	
		$V_S = 2$ V, $I_S = 8$ mA	3.0	—	—	16	
Standby current	I_{STB}	$\overline{OE} = V_{CC}$, SEL = V_{CC} or GND	3.6	—	—	10	μA
Current consumption	I_{ope}	$\overline{OE} = GND$, SEL = V_{CC} or GND	3.6	—	60	150	μA

Note: All typical values are at $T_a = 25$ °C.

12.2. High frequency characteristics (Note) (Unless otherwise specified, $V_{CC} = 1.6$ to 3.6 V)

12.2.1. TDS4A212MX

Characteristics	Symbol	Note	Test Condition	Typ.	Unit	
-3-dB Bandwidth (differential)	$BW_{(Diff)}$	(Note 1)	$R_L = 50 \Omega$, See Fig. 13.1	26.2	GHz	
Differential insertion loss	DDIL	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.1	f = 2.5 GHz	-0.6	dB
				f = 4.0 GHz	-0.7	
				f = 5.0 GHz	-0.8	
				f = 8.0 GHz	-1.0	
				f = 10.0 GHz	-1.0	
				f = 12.8 GHz	-1.2	
				f = 16.0 GHz	-1.4	
Differential return loss	DDRL	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.1	f = 2.5 GHz	-18	dB
				f = 4.0 GHz	-19	
				f = 5.0 GHz	-15	
				f = 8.0 GHz	-14	
				f = 10.0 GHz	-17	
				f = 12.8 GHz	-17	
				f = 16.0 GHz	-18	
Differential OFF isolation	DDOIRR	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.2	f = 2.5 GHz	-25	dB
				f = 4.0 GHz	-22	
				f = 5.0 GHz	-20	
				f = 8.0 GHz	-19	
				f = 10.0 GHz	-17	
				f = 12.8 GHz	-12	
				f = 16.0 GHz	-11	
Differential Crosstalk	DDXT	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.3, 13.4	f = 2.5 GHz	-40	dB
				f = 4.0 GHz	-37	
				f = 5.0 GHz	-36	
				f = 8.0 GHz	-34	
				f = 10.0 GHz	-32	
				f = 12.8 GHz	-31	
				f = 16.0 GHz	-30	

Note: All typical values are at $T_a = 25^\circ\text{C}$.

Note 1: Parameter guaranteed by design.

12.2.2. TDS4B212MX

Characteristics	Symbol	Note	Test Condition	Typ.	Unit	
-3-dB Bandwidth (differential)	$BW_{(Diff)}$	(Note 1)	$R_L = 50 \Omega$, See Fig. 13.1	27.5	GHz	
Differential insertion loss	DDIL	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.1	f = 2.5 GHz	-0.5	dB
				f = 4.0 GHz	-0.6	
				f = 5.0 GHz	-0.6	
				f = 8.0 GHz	-0.8	
				f = 10.0 GHz	-0.8	
				f = 12.8 GHz	-1.0	
Differential return loss	DDRL	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.1	f = 2.5 GHz	-20	dB
				f = 4.0 GHz	-18	
				f = 5.0 GHz	-17	
				f = 8.0 GHz	-15	
				f = 10.0 GHz	-20	
				f = 12.8 GHz	-17	
Differential OFF isolation	DDOIRR	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.2	f = 2.5 GHz	-25	dB
				f = 4.0 GHz	-21	
				f = 5.0 GHz	-20	
				f = 8.0 GHz	-17	
				f = 10.0 GHz	-16	
				f = 12.8 GHz	-17	
Differential Crosstalk	DDXT	(Note 1)	$R_L = 50 \Omega$ See Fig. 13.3, 13.4	f = 2.5 GHz	-68	dB
				f = 4.0 GHz	-60	
				f = 5.0 GHz	-56	
				f = 8.0 GHz	-48	
				f = 10.0 GHz	-44	
				f = 12.8 GHz	-39	
				f = 16.0 GHz	-36	

Note: All typical values are at $T_a = 25^\circ\text{C}$.

Note 1: Parameter guaranteed by design.

12.3. Switching Characteristics (Unless otherwise specified, $T_a = 25\text{ °C}$)

12.3.1. TDS4A212MX

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Typ.	Max	Unit
Propagation delay time	t_{PLH}/t_{PHL}	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.7	3.3	33	—	ps
Output skew (bit to bit)	$t_{SK(b)}$	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.8	3.3	6	—	ps
Output skew (channel to channel)	$t_{SK(CH)}$	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.7	3.3	6	—	ps

Note 1: Parameter guaranteed by design.

12.3.2. TDS4B212MX

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Typ.	Max	Unit
Propagation delay time	t_{PLH}/t_{PHL}	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.7	3.3	30	—	ps
Output skew (bit to bit)	$t_{SK(b)}$	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.8	3.3	4	—	ps
Output skew (channel to channel)	$t_{SK(CH)}$	(Note 1)	$R_L = 50\ \Omega$, $f = 10\text{ GHz}$ See Fig. 13.1, 13.7	3.3	2	—	ps

Note 1: Parameter guaranteed by design.

12.4. Timing characteristics

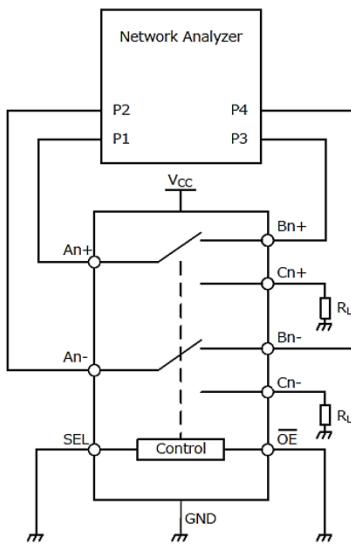
12.4.1. Timing characteristics (Unless otherwise specified, $T_a = -40\text{ to }85\text{ °C}$)

Characteristics	Symbol	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
Start-up time.	t_{sup}	See Fig. 13.5	1.65 to 3.6	—	—	100	μs
Turn-ON time (SEL to Output)	t_{on}	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.5	1.65 to 3.6	—	—	180	ns
Turn-ON time (\overline{OE} to Output)			1.65 to 3.6	—	—	100	μs
Turn-OFF time (SEL to Output)	t_{off}	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.5	1.65 to 3.6	—	—	18	ns
Turn-OFF time (\overline{OE} to Output)			1.65 to 3.6	—	—	21	ns
Break before make	TBBM	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.6	1.65 to 3.6	55	—	160	ns

12.4.2. Timing characteristics (Unless otherwise specified, $T_a = -40\text{ to }105\text{ °C}$)

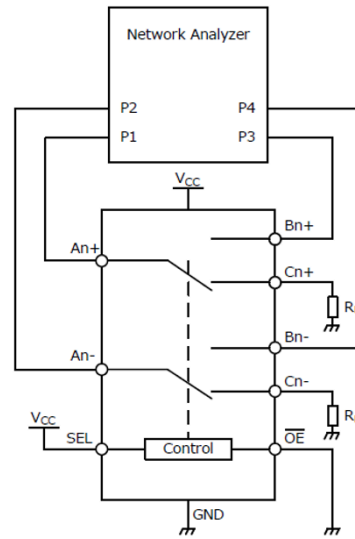
Characteristics	Symbol	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
Start-up time.	t_{sup}	See Fig. 13.5	1.65 to 3.6	—	—	110	μs
Turn-ON time (SEL to Output)	t_{on}	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.5	1.65 to 3.6	—	—	180	ns
Turn-ON time (\overline{OE} to Output)			1.65 to 3.6	—	—	110	μs
Turn-OFF time (SEL to Output)	t_{off}	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.5	1.65 to 3.6	—	—	20	ns
Turn-OFF time (\overline{OE} to Output)			1.65 to 3.6	—	—	25	ns
Break before make	TBBM	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ See Fig. 13.6	1.65 to 3.6	55	—	160	ns

13. AC Electrical Test Circuit (Fig)



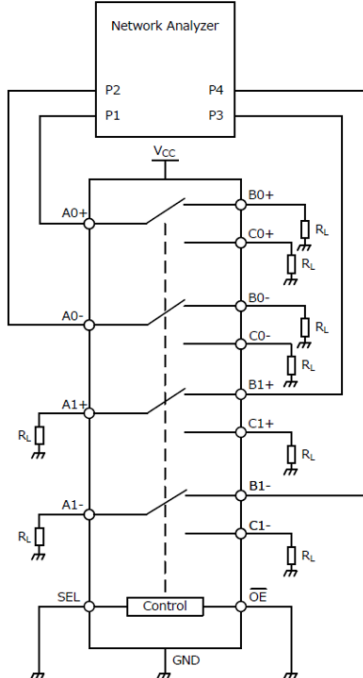
$R_L = 50 \Omega$
 All unused ports are connected to GND through 50Ω pull-down resistors.
 This figure is an example showing how to measure An and Bn.

Fig. 13.1 -3-dB Bandwidth(differential), Differential insertion loss, Differential return loss, Propagation delay time, Output skew (channel to channel, bit to bit)



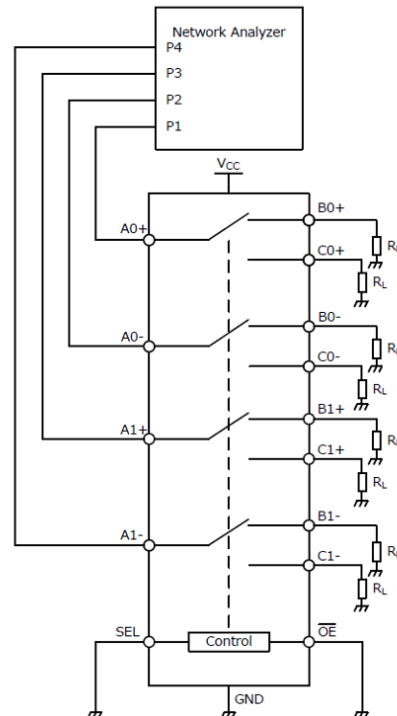
$R_L = 50 \Omega$
 All unused ports are connected to GND through 50Ω pull-down resistors.
 This figure is an example showing how to measure An and Bn.

Fig. 13.2 Differential OFF isolation



$R_L = 50 \Omega$
 All unused ports are connected to GND through 50Ω pull-down resistors.
 This figure is an example showing how to measure A0 and B1.

Fig. 13.3 Differential Far-end crosstalk



$R_L = 50 \Omega$
 All unused ports are connected to GND through 50Ω pull-down resistors.
 This figure is an example showing how to measure A0 and A1.

Fig. 13.4 Differential Near-end crosstalk

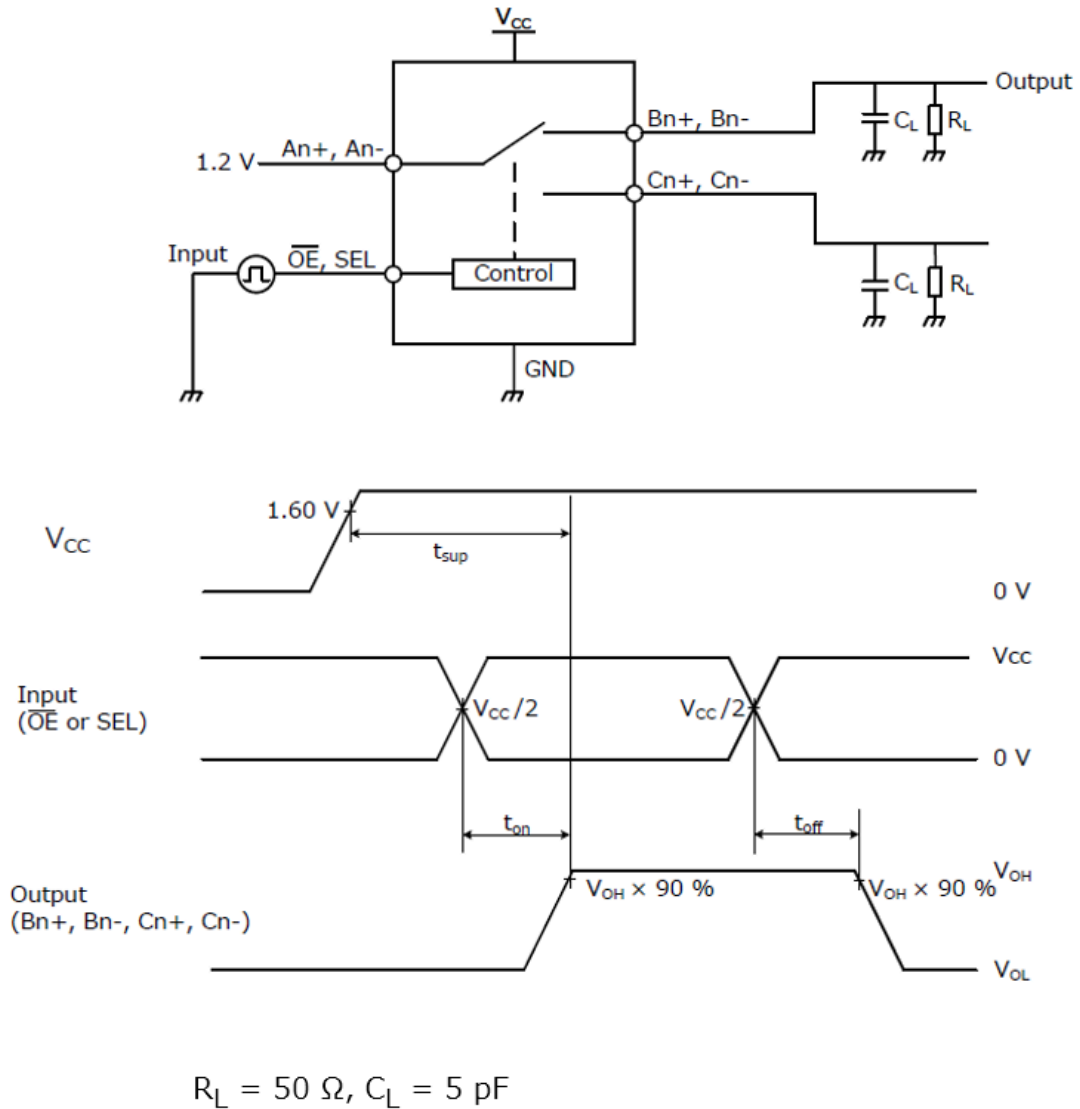
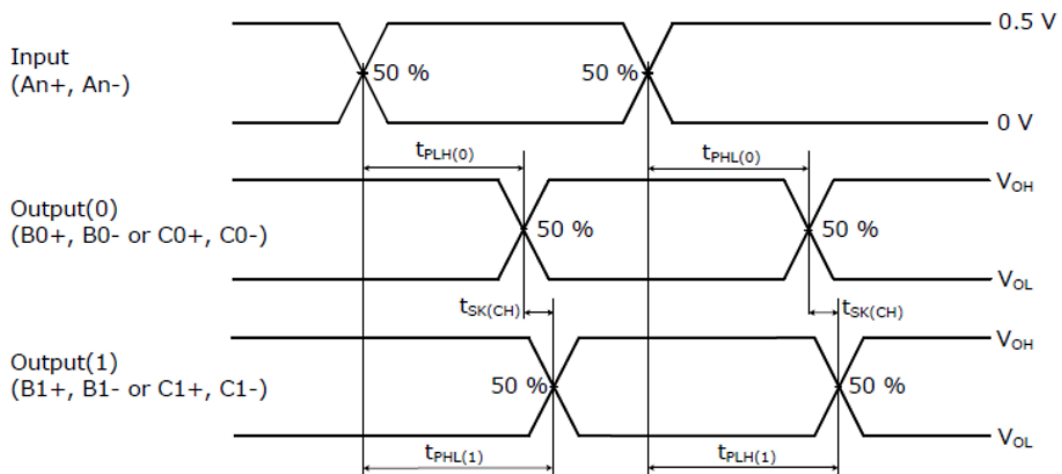
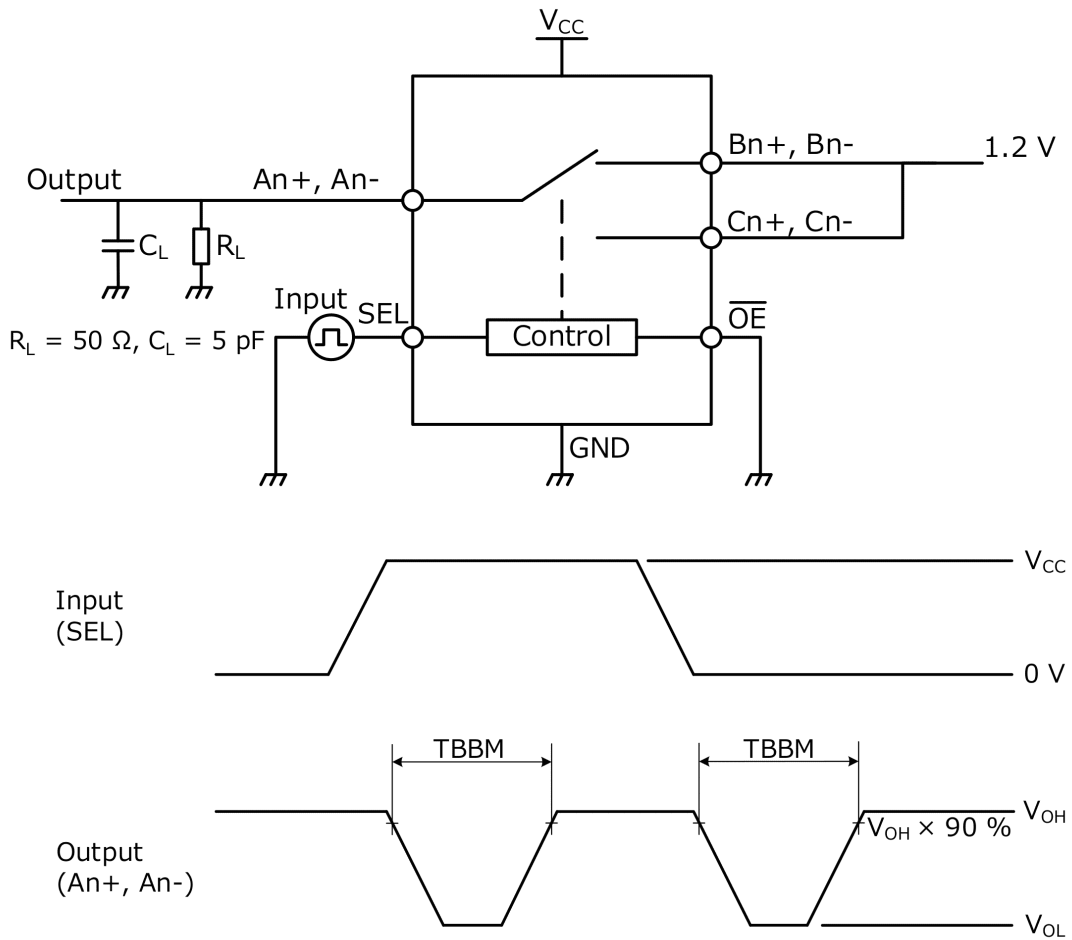


Fig. 13.5 Start-up, Turn-ON and Turn-OFF time



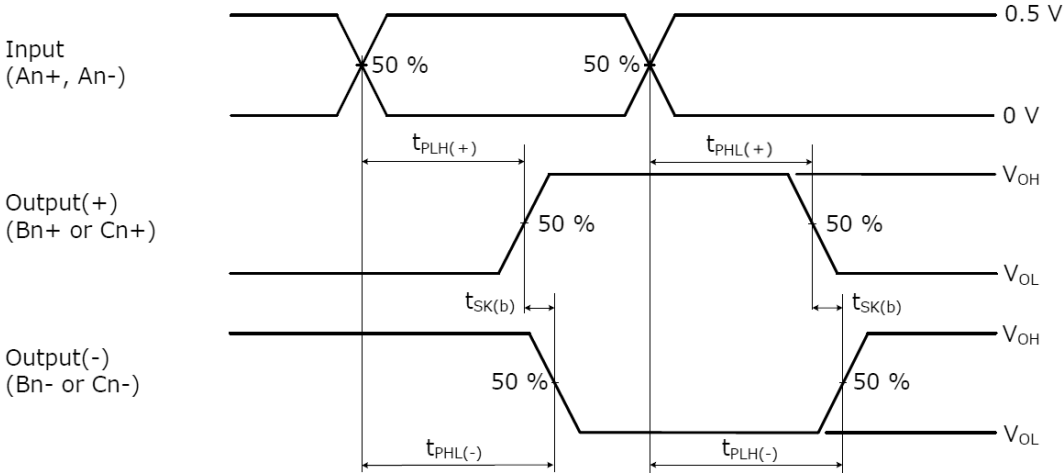
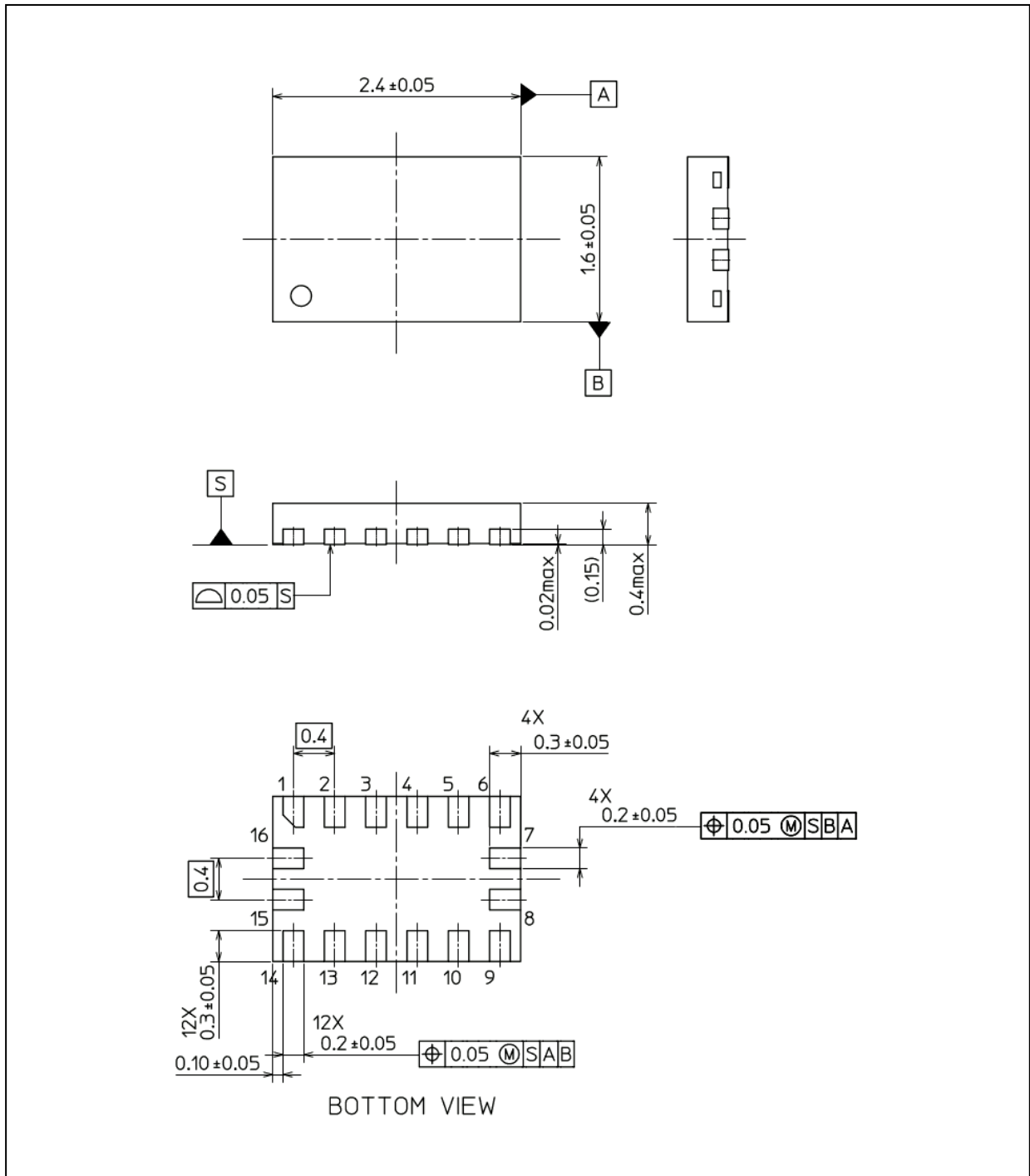


Fig. 13.8 Output skew (bit to bit)

Package Dimensions

Unit: mm



Weight: 3.9 mg (typ.)

Package Name(s)
Nickname: XQFN16

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